

# DATA SHEET

**74ABT16841A**  
**74ABTH16841A**  
20-bit bus interface latch (3-State)

Product specification  
Supersedes data of 1995 Sep 28  
IC23 Data Handbook

1998 Feb 27

## 20-bit bus interface latch (3-State)

**74ABT16841A**  
**74ABTH16841A**

### FEATURES

- High speed parallel latches
- Live insertion/extraction permitted
- Extra data width for wide address/data paths or buses carrying parity
- Power-up 3-State
- 74ABTH16841A incorporates bus-hold data inputs which eliminate the need for external pull-up resistors to hold unused inputs
- Power-up reset
- Ideal where high speed, light loading, or increased fan-in are required with MOS microprocessors
- Output capability: +64mA/–32mA
- Latch-up protection exceeds 500mA per Jedec Std 17
- ESD protection exceeds 2000V per MIL STD 883 Method 3015 and 200V per Machine Model

### DESCRIPTION

The 74ABT16841A Bus interface latch is designed to provide extra data width for wider data/address paths of buses carrying parity.

The 74ABT16841A consists of two sets of ten D-type latches with 3-State outputs. The flip-flops appear transparent to the data when Latch Enable (nLE) is High. This allows asynchronous operation, as the output transition follows the data in transition. On the nLE High-to-Low transition, the data that meets the setup and hold time is latched.

Data appears on the bus when the Output Enable (nOE) is Low. When nOE is High the output is in the High-impedance state.

Two options are available, 74ABT16841A which does not have the bus-hold feature and 74ABTH16841A which incorporates the bus-hold feature.

### QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS $T_{amb} = 25^{\circ}\text{C}; \text{GND} = 0\text{V}$	TYPICAL	UNIT
$t_{PLH}$ $t_{PHL}$	Propagation delay nDx to nQx	$C_L = 50\text{pF}; V_{CC} = 5\text{V}$	3.1 2.2	ns
$C_{IN}$	Input capacitance	$V_I = 0\text{V}$ or $V_{CC}$	4	pF
$C_{OUT}$	Output capacitance	$V_O = 0\text{V}$ or $V_{CC}$ ; 3-State	7	pF
$I_{CCZ}$	Quiescent supply current	Outputs disabled; $V_{CC} = 5.5\text{V}$	500	$\mu\text{A}$
$I_{CCL}$		Outputs LOW; $V_{CC} = 5.5\text{V}$	10	mA

### ORDERING INFORMATION

PACKAGES	TEMPERATURE RANGE	OUTSIDE NORTH AMERICA	NORTH AMERICA	DWG NUMBER
56-Pin Plastic SSOP Type III	–40°C to +85°C	74ABT16841A DL	BT16841A DL	SOT371-1
56-Pin Plastic TSSOP Type II	–40°C to +85°C	74ABT16841A DGG	BT16841A DGG	SOT364-1
56-Pin Plastic SSOP Type III	–40°C to +85°C	74ABTH16841A DL	BH16841A DL	SOT371-1
56-Pin Plastic TSSOP Type II	–40°C to +85°C	74ABTH16841A DGG	BH16841A DGG	SOT364-1

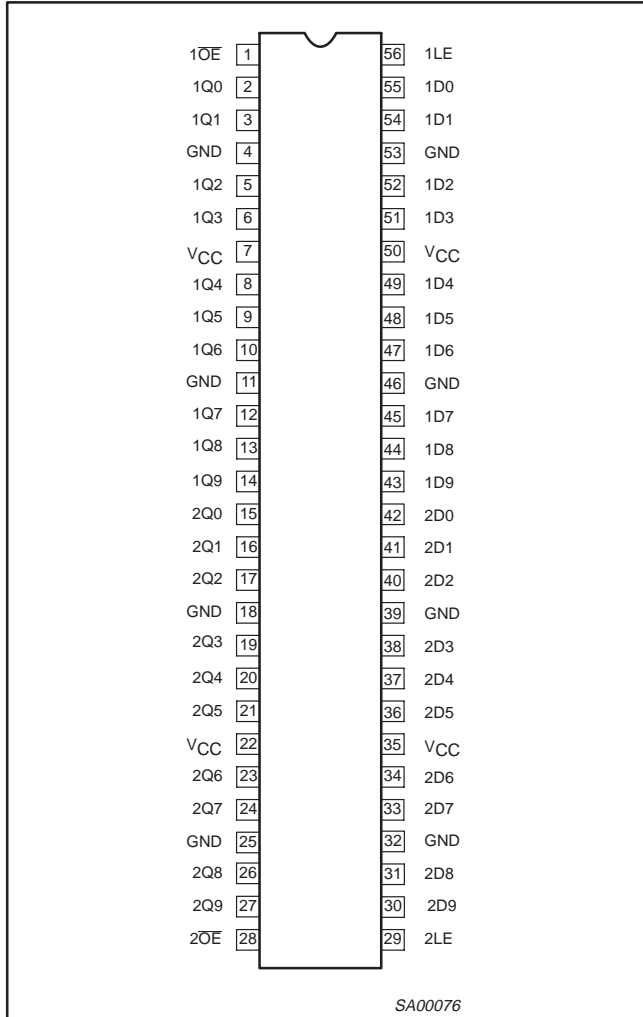
### PIN DESCRIPTION

PIN NUMBER	SYMBOL	FUNCTION
55, 54, 52, 51, 49, 48, 47, 45, 44, 43 42, 41, 40, 38, 37, 36, 34, 33, 31, 30	1D0 – 1D9 2D0 – 2D9	Data inputs
2, 3, 5, 6, 8, 9, 10, 12, 13, 14 15, 16, 17, 19, 20, 21, 23, 24, 26, 27	1Q0 – 1Q9 2Q0 – 2Q9	Data outputs
1, 28	1OE, 2OE	Output enable inputs (active-Low)
56, 29	1LE, 2LE	Latch enable inputs (active rising edge)
4, 11, 18, 25, 32, 39, 46, 53	GND	Ground (0V)
7, 22, 35, 50	$V_{CC}$	Positive supply voltage

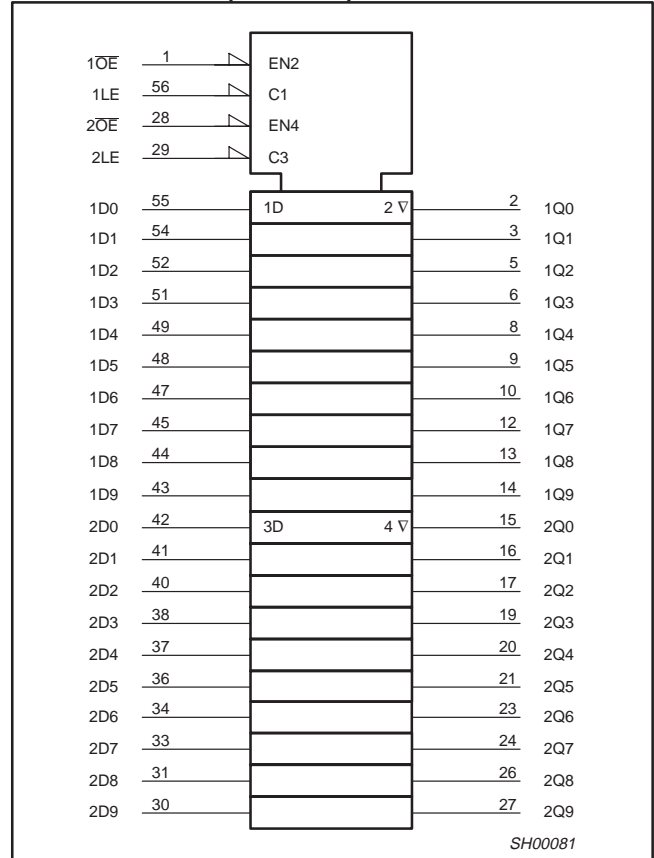
# 20-bit bus interface latch (3-State)

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74ABTH16841A

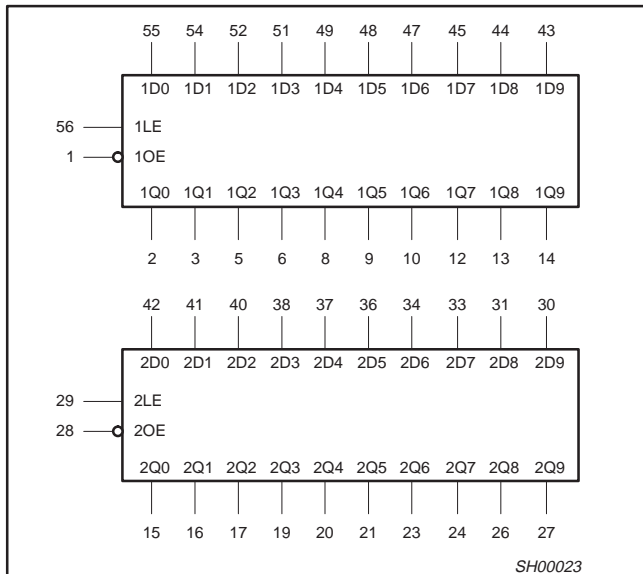
## PIN CONFIGURATION



## LOGIC SYMBOL (IEEE/IEC)



## LOGIC SYMBOL



## FUNCTION TABLE

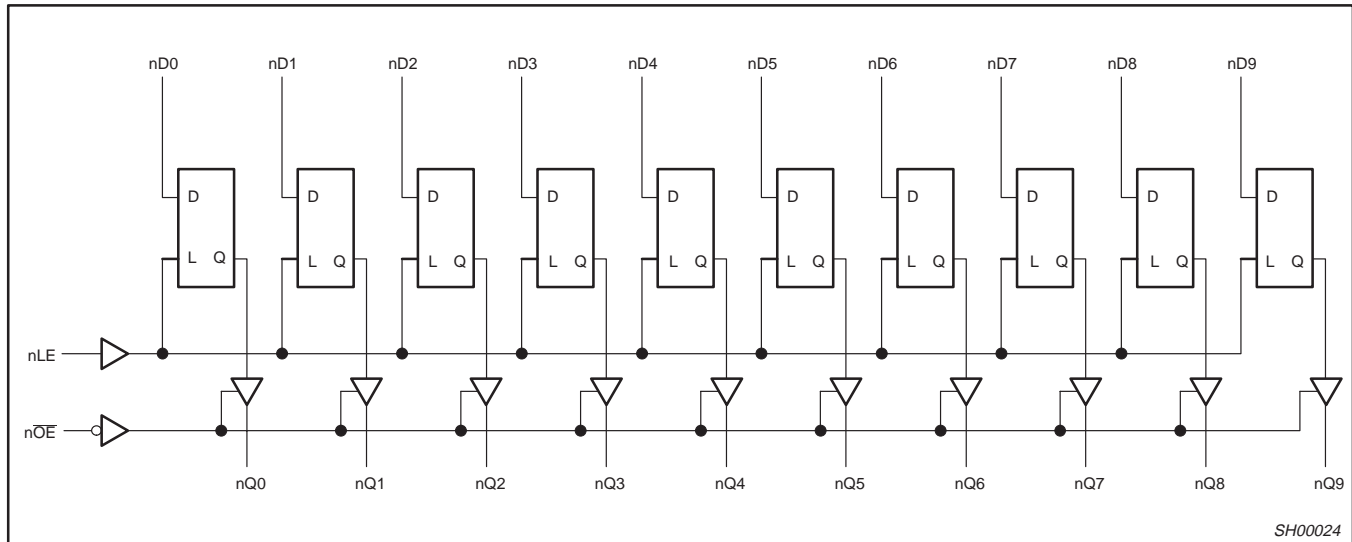
INPUTS			OUTPUTS	OPERATING MODE
nOE	nLE	nDx	nQ0 – nQ9	
L	H	L	L	Transparent
L	H	H	H	
L	↓	l	L	Latched
L	↓	h	H	
H	X	X	Z	High impedance
L	L	X	NC	Hold

- H = High voltage level
- h = High voltage level one set-up time prior to the High-to-Low LE transition
- L = Low voltage level
- l = Low voltage level one set-up time prior to the High-to-Low LE transition
- ↓ = High-to-Low LE transition
- NC= No change
- X = Don't care
- Z = High impedance "off" state

# 20-bit bus interface latch (3-State)

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## LOGIC DIAGRAM



## ABSOLUTE MAXIMUM RATINGS<sup>1, 2</sup>

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
V <sub>CC</sub>	DC supply voltage		-0.5 to +7.0	V
I <sub>IK</sub>	DC input diode current	V <sub>I</sub> < 0	-18	mA
V <sub>I</sub>	DC input voltage <sup>3</sup>		-1.2 to +7.0	V
I <sub>OK</sub>	DC output diode current	V <sub>O</sub> < 0	-50	mA
V <sub>OUT</sub>	DC output voltage <sup>3</sup>	Output in Off or High state	-0.5 to +5.5	V
I <sub>OUT</sub>	DC output current	Output in Low state	128	mA
		Output in High state	-64	
T <sub>stg</sub>	Storage temperature range		-65 to 150	°C

### NOTES:

- Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability. The maximum junction temperature of this integrated circuit should not exceed 150°C.
- The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

## RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	LIMITS		UNIT
		Min	Max	
V <sub>CC</sub>	DC supply voltage	4.5	5.5	V
V <sub>I</sub>	Input voltage	0	V <sub>CC</sub>	V
V <sub>IH</sub>	High-level input voltage	2.0		V
V <sub>IL</sub>	Low-level Input voltage		0.8	V
I <sub>OH</sub>	High-level output current		-32	mA
I <sub>OL</sub>	Low-level output current		64	mA
Δt/Δv	Input transition rise or fall rate	0	5	ns/V
T <sub>amb</sub>	Operating free-air temperature range	-40	+85	°C

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## DC ELECTRICAL CHARACTERISTICS

SYMBOL	PARAMETER	TEST CONDITIONS	LIMITS					UNIT
			T <sub>amb</sub> = +25°C			T <sub>amb</sub> = -40°C to +85°C		
			Min	Typ	Max	Min	Max	
V <sub>IK</sub>	Input clamp voltage	V <sub>CC</sub> = 4.5V; I <sub>IK</sub> = -18mA		-0.9	-1.2		-1.2	V
V <sub>OH</sub>	High-level output voltage	V <sub>CC</sub> = 4.5V; I <sub>OH</sub> = -3mA; V <sub>I</sub> = V <sub>IL</sub> or V <sub>IH</sub>	2.5	2.9		2.5		V
		V <sub>CC</sub> = 5.0V; I <sub>OH</sub> = -3mA; V <sub>I</sub> = V <sub>IL</sub> or V <sub>IH</sub>	3.0	3.4		3.0		V
		V <sub>CC</sub> = 4.5V; I <sub>OH</sub> = -32mA; V <sub>I</sub> = V <sub>IL</sub> or V <sub>IH</sub>	2.0	2.4		2.0		V
V <sub>OL</sub>	Low-level output voltage	V <sub>CC</sub> = 4.5V; I <sub>OL</sub> = 64mA; V <sub>I</sub> = V <sub>IL</sub> or V <sub>IH</sub>		0.42	0.55		0.55	V
V <sub>RST</sub>	Power-up output voltage <sup>3</sup>	V <sub>CC</sub> = 5.5V; I <sub>O</sub> = 1mA; V <sub>I</sub> = GND or V <sub>CC</sub>		0.13	0.55		0.55	V
I <sub>I</sub>	Input leakage current 74ABT16841A	V <sub>CC</sub> = 5.5V; V <sub>I</sub> = V <sub>CC</sub> or GND		±0.01	±1		±1.0	µA
I <sub>I</sub>	Input leakage current 74ABTH16841A	V <sub>CC</sub> = 5.5V; V <sub>I</sub> = V <sub>CC</sub> or GND	Control pins	±0.01	±1		±1	µA
		V <sub>CC</sub> = 5.5V; V <sub>I</sub> = V <sub>CC</sub>	Data pins <sup>5</sup>	0.01	1		1	µA
		V <sub>CC</sub> = 5.5V; V <sub>I</sub> = 0		-2	-3		-5	µA
I <sub>HOLD</sub>	Bus Hold current inputs <sup>6</sup> 74ABTH16841A	V <sub>CC</sub> = 4.5V; V <sub>I</sub> = 0.8V		35		35		µA
		V <sub>CC</sub> = 4.5V; V <sub>I</sub> = 2.0V		-75		-75		
		V <sub>CC</sub> = 5.5V; V <sub>I</sub> = 0 to 5.5V		±800				
I <sub>OFF</sub>	Power-off leakage current	V <sub>CC</sub> = 0.0V; V <sub>O</sub> or V <sub>I</sub> ≤ 4.5V		±5.0	±100		±100	µA
I <sub>PU/PD</sub>	Power-up/down 3-State output current <sup>4</sup>	V <sub>CC</sub> = 2.1V; V <sub>O</sub> = 0.5V; V <sub>I</sub> = GND or V <sub>CC</sub> ; V <sub>OE</sub> = Don't care		±5.0	±50		±50	µA
I <sub>OZH</sub>	3-State output High current	V <sub>CC</sub> = 5.5V; V <sub>O</sub> = 2.7V; V <sub>I</sub> = V <sub>IL</sub> or V <sub>IH</sub>		5.0	10		10	µA
I <sub>OZL</sub>	3-State output Low current	V <sub>CC</sub> = 5.5V; V <sub>O</sub> = 0.5V; V <sub>I</sub> = V <sub>IL</sub> or V <sub>IH</sub>		-5.0	-10		-10	µA
I <sub>CEX</sub>	Output High leakage current	V <sub>CC</sub> = 5.5V; V <sub>O</sub> = 5.5V; V <sub>I</sub> = GND or V <sub>CC</sub>		5.0	50		50	µA
I <sub>O</sub>	Output current <sup>1</sup>	V <sub>CC</sub> = 5.5V; V <sub>O</sub> = 2.5V	-50	-70	-180	-50	-180	mA
I <sub>CCH</sub>	Quiescent supply current	V <sub>CC</sub> = 5.5V; Outputs High, V <sub>I</sub> = GND or V <sub>CC</sub>		0.5	1		1	mA
I <sub>CCL</sub>		V <sub>CC</sub> = 5.5V; Outputs Low, V <sub>I</sub> = GND or V <sub>CC</sub>		10	19		19	mA
I <sub>CCZ</sub>		V <sub>CC</sub> = 5.5V; Outputs 3-State; V <sub>I</sub> = GND or V <sub>CC</sub>		0.5	1		1	mA
ΔI <sub>CC</sub>	Additional supply current per input pin <sup>2</sup>	V <sub>CC</sub> = 5.5V; one input at 3.4V, other inputs at V <sub>CC</sub> or GND		0.2	1		1	mA

## NOTES:

- Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
- This is the increase in supply current for each input at 3.4V.
- For valid test results, data must not be loaded into the flip-flops (or latches) after applying the power.
- This parameter is valid for any V<sub>CC</sub> between 0V and 2.1V with a transition time of up to 10msec. From V<sub>CC</sub> = 2.1V to V<sub>CC</sub> = 5V ± 10% a transition time of up to 100µsec is permitted.
- Unused pins at V<sub>CC</sub> or GND.
- This is the bus hold overdrive current required to force the input to the opposite logic state.

## AC CHARACTERISTICS

GND = 0V, t<sub>R</sub> = t<sub>F</sub> = 2.5ns, C<sub>L</sub> = 50pF, R<sub>L</sub> = 500Ω

SYMBOL	PARAMETER	WAVEFORM	LIMITS					UNIT
			T <sub>amb</sub> = +25°C V <sub>CC</sub> = +5.0V			T <sub>amb</sub> = -40 to +85°C V <sub>CC</sub> = +5.0V ±0.5V		
			MIN	TYP	MAX	MIN	MAX	
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay nDx to nQx	2	1.1 1.5	3.1 2.2	4.1 3.1	1.1 1.5	4.9 3.6	ns
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay nLE to nQx	1	1.5 1.0	2.5 2.1	3.3 2.8	1.5 1.0	3.7 3.1	ns
t <sub>PZH</sub> t <sub>PZL</sub>	Output enable time to High and Low level	4 5	1.2 1.2	2.4 2.2	3.2 2.9	1.2 1.2	4.0 3.6	ns
t <sub>PHZ</sub> t <sub>PLZ</sub>	Output disable time from High and Low level	4 5	1.8 1.5	3.0 2.5	4.0 3.2	1.8 1.5	4.9 3.7	ns

# 20-bit bus interface latch (3-State)

74ABT16841A  
74ABTH16841A

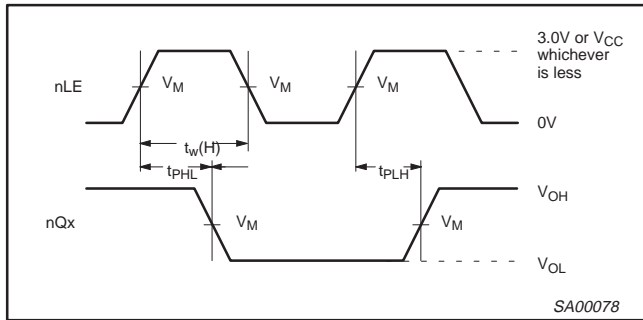
## AC SETUP REQUIREMENTS

GND = 0V,  $t_R = t_F = 2.5\text{ns}$ ,  $C_L = 50\text{pF}$ ,  $R_L = 500\Omega$

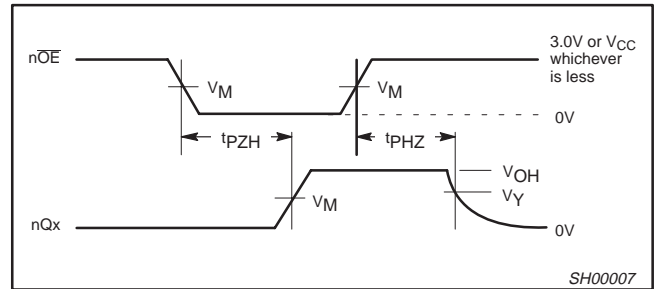
SYMBOL	PARAMETER	WAVEFORM	LIMITS				UNIT
			$T_{\text{amb}} = +25^\circ\text{C}$ $V_{\text{CC}} = +5.0\text{V}$		$T_{\text{amb}} = -40 \text{ to } +85^\circ\text{C}$ $V_{\text{CC}} = +5.0\text{V} \pm 0.5\text{V}$		
			Min	Typ	Min	Max	
$t_s(\text{H})$ $t_s(\text{L})$	Setup time, High or Low nDx to nLE	3	2.0 1.0	1.0 0.4	2.0 1.0		ns
$t_h(\text{H})$ $t_h(\text{L})$	Hold time, High or Low nDx to nLE	3	2.0 2.0	-0.3 -0.7	2.0 2.0		ns
$t_w(\text{H})$	nLE pulse width High	1	2.9	1.9	2.9		ns

## AC WAVEFORMS

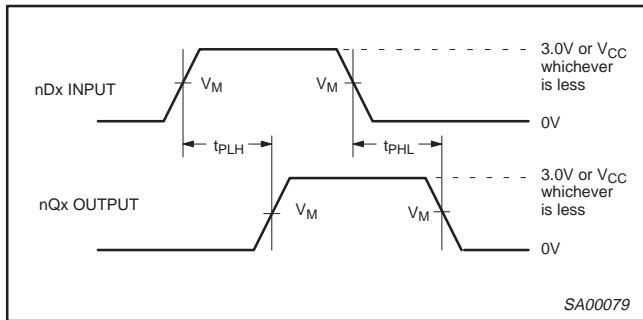
$V_M = 1.5\text{V}$ ,  $V_{\text{IN}} = \text{GND to } 3.0\text{V}$



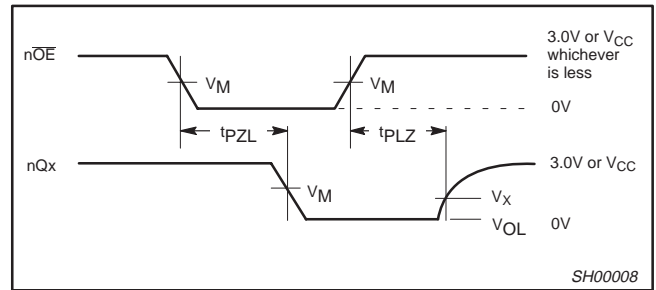
Waveform 1. Propagation Delay, Latch Enable Input to Output, and Enable Pulse Width



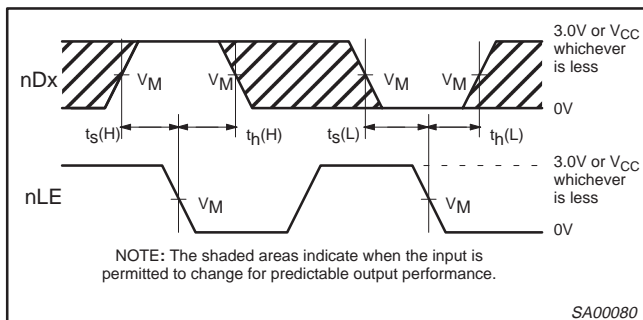
Waveform 4. 3-State Output Enable Time to High Level and Output Disable Time from High Level



Waveform 2. Propagation Delay for Data to Outputs



Waveform 5. 3-State Output Enable Time to Low Level and Output Disable Time from Low Level

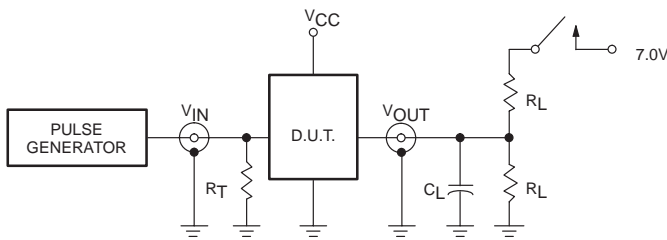


Waveform 3. Data Setup and Hold Times

# 20-bit bus interface latch (3-State)

74ABT16841A  
74ABTH16841A

## TEST CIRCUIT AND WAVEFORM



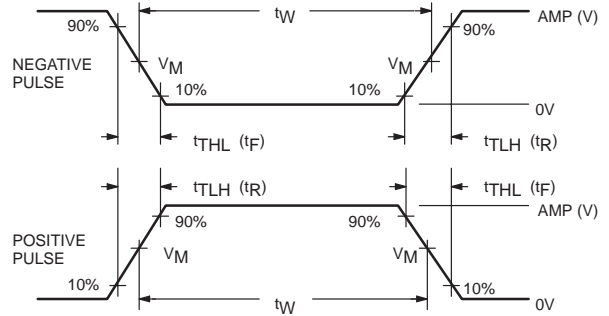
Test Circuit for 3-State Outputs

### SWITCH POSITION

TEST	SWITCH
$t_{PLZ}$	closed
$t_{PZL}$	closed
All other	open

### DEFINITIONS

- $R_L$  = Load resistor; see AC CHARACTERISTICS for value.
- $C_L$  = Load capacitance includes jig and probe capacitance; see AC CHARACTERISTICS for value.
- $R_T$  = Termination resistance should be equal to  $Z_{OUT}$  of pulse generators.



$V_M = 1.5V$   
Input Pulse Definition

FAMILY	INPUT PULSE REQUIREMENTS				
	Amplitude	Rep. Rate	$t_W$	$t_R$	$t_F$
74ABT/H16	3.0V	1MHz	500ns	2.5ns	2.5ns

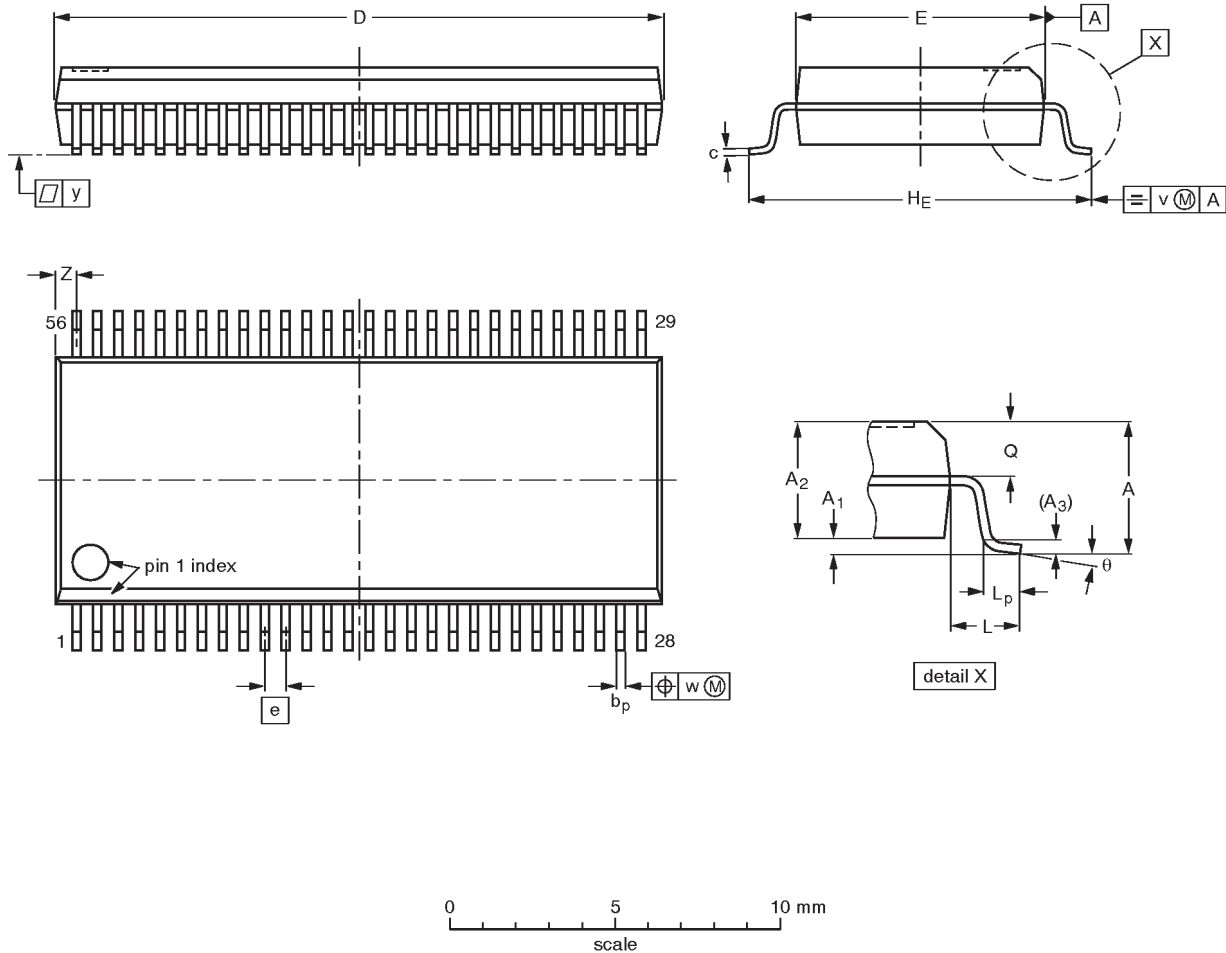
SA00018

20-bit bus interface latch (3-State)

74ABT16841A  
74ABTH16841A

SSOP56: plastic shrink small outline package; 56 leads; body width 7.5 mm

SOT371-1



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	E <sup>(1)</sup>	e	H <sub>E</sub>	L	L <sub>p</sub>	Q	v	w	y	Z <sup>(1)</sup>	θ
mm	2.8	0.4 0.2	2.35 2.20	0.25	0.3 0.2	0.22 0.13	18.55 18.30	7.6 7.4	0.635	10.4 10.1	1.4	1.0 0.6	1.2 1.0	0.25	0.18	0.1	0.85 0.40	8° 0°

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT371-1		MO-118AB				93-11-02 95-02-04

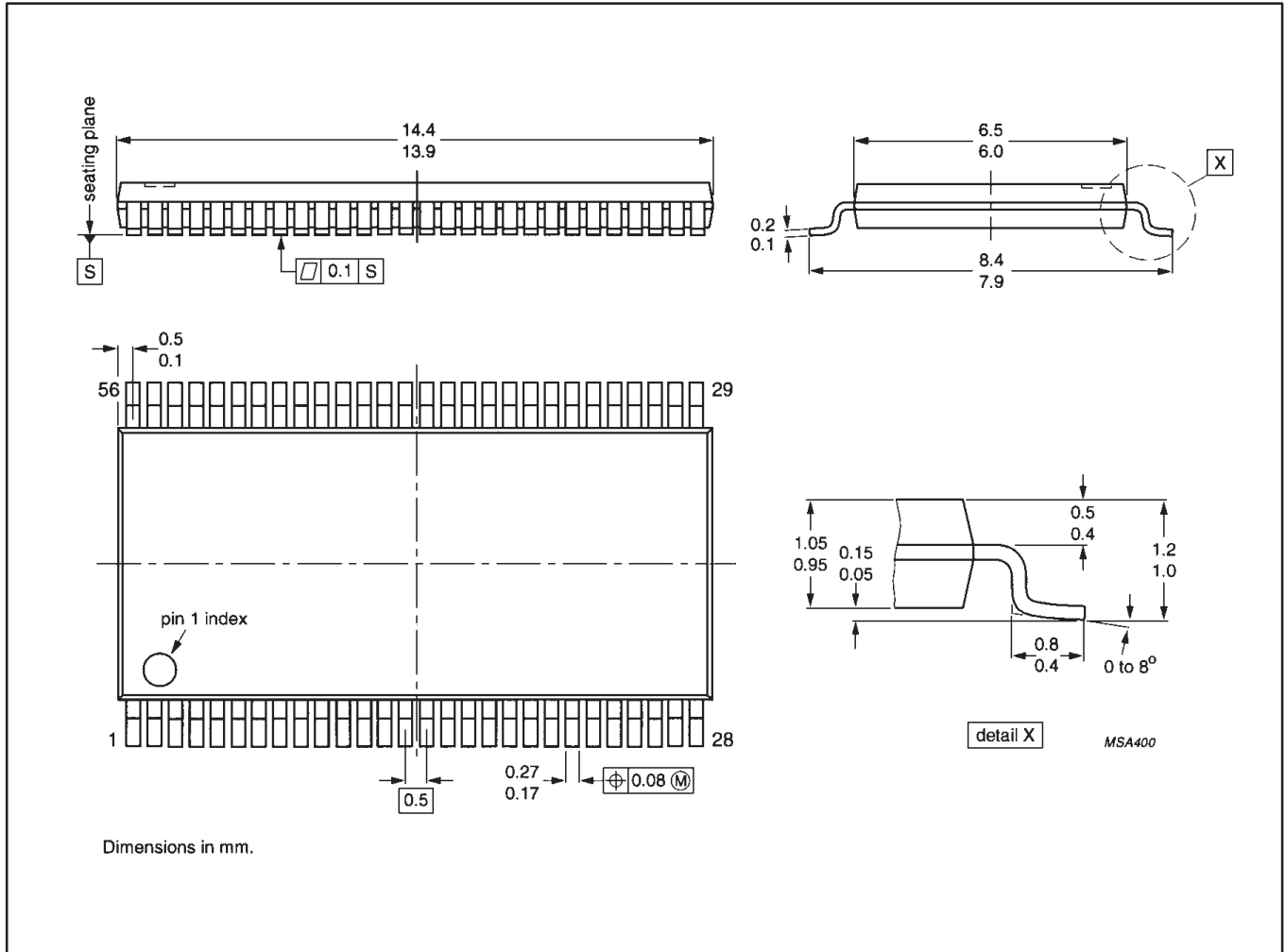


# 20-bit bus interface latch (3-State)

74ABT16841A  
74ABTH16841A

TSSOP56: plastic thin shrink small outline package; 56 leads; body width 6.1mm

SOT364-1



## 20-bit bus interface latch (3-State)

74ABT16841A  
74ABTH16841A

## Data sheet status

Data sheet status	Product status	Definition [1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
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[1] Please consult the most recently issued datasheet before initiating or completing a design.

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